PIXEL 2012

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Silicon Detectors for the HL-LHC - Recent RD50 Results -

RD50 Objectives

Material characterisation & defect engineering

- Understanding of radiation damage
 - Macroscopic effects and microscopic effects
 - Irradiation with different particles (p, n, π)
 - Oxygen enrichment
 - DOFZ, Cz, MCz, EPI
- Understanding/tuning of influence of processing technology

Device Engineering

- p-type silicon (n-in-p)
- thin sensors
- 3D detectors

➔ Proposal/understanding which sensor material and/or sensor configuration can be used at which radius to the beam for the HL-LHC and beyond.

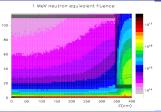
Radiation Challenge (HL-LHC)

(cu)

Radiation levels, including safety factor of 2:

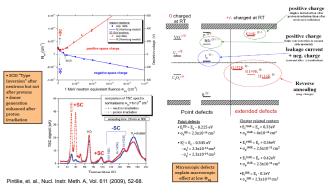
Innermost Pixel Layer: Outer Pixel Layers: Short strips: Long strips:

r: $1 \times 10^{16} n_{eq}/cm^2$ $3 \times 10^{15} n_{eq}/cm^2$ $1 \times 10^{15} n_{eq}/cm^2$ $4 \times 10^{14} n_{eq}/cm^2$

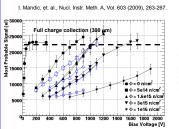


Microscopic studies RD50/WODEAN

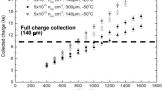
Systematic studies to understand microscopic band levels correspondence to their macroscopic behaviour



Charge Multiplication



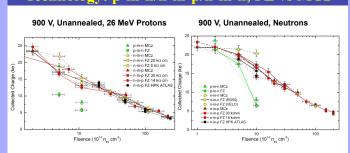




More than 100% charge collection seen at high bias voltages after irradiation for both n-in-p strips and EPI

- Multiplication is consistent with high fields at implants
- Multiplication largest at segmented implant
 Current also correlated with charge as expected

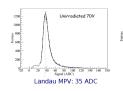
Technology: p-in-n/n-in-p/n-in-n, FZ vs MCz



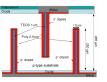
- CCE crucial for high fluences.
- Different bulk materials irradiated with charged and neutral particles.
- p-in-n not radiation tolerant enough for inner HL-LHC radii
- No CCE annealing observed for p-bulk
 N-strip readout devices devices have sufficient CCE for even innermost HL-LHC radii

Micron Neutrons: A. Affolder, et. al., Nucl. Instr. Meth. A, Vol. 612 (2010), 470-473. Micron 26 MeV Protons: A. Affolder, et. al., Nucl. Instr. Meth. A, Vol. 623 (2010), 177-179. HPK Neutrons: K. Hara, et. at., Nucl. Inst. Meth. A, Vol. 636 (2011) S83-S89.

Device Engineering, **3D**







Narrow columns along the detector thickness

- Diameter: 10µm, distance 50-100µm
 - Lower depletion voltage needed Double sided p-type sensors (CNM) in SPS
- testbeam Irradiation at Karlsruhe) with 26MeV protons Higher signal after irradiation than before (multiplication)

Conclusions

At fluences up to 10¹⁵ n_{ea}cm⁻² (Outer radii of HL-LHC):

- MCz silicon detectors detectors could be a solution (more work still needed)
- P-type silicon microstrip detectors show promising results:
 - CCE ≈ 6500e, Φ_{eq}=4 × 10¹⁵cm⁻², V=500V, 300µm, immunity
 - against reverse annealing
 - Presently the baseline option for ATLAS upgrade.

At fluences up to $10^{16} n_{eq} \text{ cm}^{-2}$ (Inner radii of HL-LHC):

Collection of electrons at electrodes essential. Use n-in-n or n-in-p detectors.

- Recent results show that planar silicon sensors will still have sufficient signal
- 3D detectors look promising

Many collaborations and sensor producers are working on this.